Patent claims

1. An implant comprising:
   - a substrate ~~(1)~~;
   - a first housing ~~(2)~~, wherein the first housing ~~(2)~~ is disposed on the substrate ~~(1)~~;
   - a~~n~~ first electronic circuit ~~(3)~~ disposed on the substrate ~~(1)~~ inside the first housing ~~(2)~~;
   - an electronic component ~~(5)~~ disposed on the substrate ~~(1)~~ outside the first housing ~~(2)~~;
   - a conductor track ~~(6)~~, wherein the conductor track ~~(6)~~ connects the first electronic circuit ~~(3)~~ to the electronic component ~~(5)~~;

   wherein the conductor track ~~(6)~~ is embedded into the substrate ~~(1)~~ at least in sections in such a way that at least one section of the conductor track ~~(6)~~ is completely surrounded by the substrate ~~(1)~~, and wherein the substrate is made of a thermoplastic, and the first housing is made of a thermoplastic.

2. The implant according to claim 1, wherein the conductor track ~~(6)~~ is completely embedded into the substrate ~~(1)~~ in such a way that the conductor track ~~(6)~~ is surrounded by the substrate ~~(1)~~ across the entire length thereof.

3. The implant according to claim 1 or 2, wherein the electronic component ~~(5)~~ is an electrode ~~(5a)~~ or a sensor ~~(5b)~~.

4. The implant according to any one of the preceding claims, wherein multiple electronic components ~~(5, 5a, 5b)~~ are disposed on the substrate ~~(1)~~ outside the first housing ~~(2)~~, the multiple electronic components ~~(5, 5a, 5b)~~ being connected to the first electronic circuit ~~(3)~~ by way of multiple conductor tracks ~~(6)~~, and the multiple conductor tracks ~~(6)~~ being embedded into the substrate ~~(1)~~ at least in sections in such a way that, for

each conductor track ~~(6)~~, at least one section of the respective conductor track ~~(6)~~ is completely surrounded by the substrate ~~(1)~~.

5. The implant according to any one of the preceding claims, wherein the substrate ~~(1)~~ is a multi-layer substrate, and at least one section of the conductor track ~~(6)~~ is embedded between two layers of the multi-layer substrate.

~~6. The implant according to any one of the preceding claims, wherein the substrate (1) is made of a thermoplastic.~~

~~7. The implant according to any one of the preceding claims, wherein the first housing (2) is made of a thermoplastic.~~

~~8~~6. The implant according to any one of the preceding claims, wherein the substrate ~~(1)~~ and the first housing ~~(2)~~ are made of the same material.

~~9~~7. The implant according to any one of the preceding claims, wherein a second housing ~~(8)~~ is disposed on the substrate ~~(1)~~, and a second electronic circuit ~~(9)~~ is disposed on the substrate ~~(1)~~ inside the second housing ~~(8)~~.

~~10~~8. The implant according to claim ~~9~~7, wherein the first housing ~~(2)~~ comprising the first electronic circuit ~~(3)~~ and the second housing ~~(8)~~ comprising the second electronic circuit ~~(9)~~ are disposed on the same side of the substrate ~~(1)~~.

~~11~~9. The implant according to claim ~~10~~8, wherein the first housing ~~(2)~~ and the second housing ~~(8)~~ are disposed at a distance from one another, and the substrate ~~(1)~~ is flexible in a region ~~(16)~~ between the first housing ~~(2)~~ and the second housing ~~(8)~~.

~~12~~10. The implant according to claim ~~9~~7, wherein the first housing ~~(2)~~ comprising the first electronic circuit ~~(3)~~ is disposed on a first side ~~(21)~~ of the substrate ~~(1)~~, and the second housing ~~(8)~~ comprising the second electronic circuit ~~(9)~~ is disposed on a second side ~~(22)~~ of the substrate ~~(1)~~, the second side ~~(22)~~ being situated opposite the first side ~~(21)~~.

13~~1~~. The implant according to any one of the preceding claims, wherein a coil ~~(19)~~ is integrated into the first housing ~~(2)~~.

14~~2~~. A method for creating an implant, comprising the following steps:

- disposing a~~n~~ first electronic circuit ~~(3)~~ on a substrate ~~(1)~~;
- disposing a first housing ~~(2)~~ on the substrate ~~(1)~~ in such a way that the first electronic circuit ~~(3)~~ is disposed inside the first housing ~~(2)~~;
- disposing an electronic component ~~(5)~~ on the substrate ~~(1)~~ outside the first housing ~~(2)~~; and
- establishing a connection between the first electronic circuit ~~(3)~~ and the electronic component ~~(5)~~ by way of a conductor track ~~(6)~~,

wherein the conductor track ~~(6)~~ is embedded into the substrate ~~(1)~~ at least in sections in such a way that at least one section of the conductor track ~~(6)~~ is completely surrounded by the substrate ~~(1)~~, and wherein
the substrate is made of a thermoplastic, and
the first housing is made of a thermoplastic.